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DATE MAILED: 09/23/2004

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/681,274	10/09/2003	Yoshikazu Ohara	4074-8	5972
23117 7	590 09/23/2004		EXAMINER	
NIXON & VANDERHYE, PC			DICKEY, THOMAS L	
1100 N GLEBI 8TH FLOOR	E ROAD		ART UNIT	PAPER NUMBER
	VA 22201-4714		2826	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)	
		10/681,274	OHARA, YOSHIKAZU	
	Office Action Summary	Examiner	Art Unit	
		Thomas L Dickey	2826	
Period fo	The MAILING DATE of this communication app	pears on the cover sheet with the c	orrespondence addi	ess
A SH THE - Exter after - If the - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR REPL' MAILING DATE OF THIS COMMUNICATION. nsions of time may be available under the provisions of 37 CFR 1.1: SIX (6) MONTHS from the mailing date of this communication. e period for reply specified above is less than thirty (30) days, a reply b period for reply is specified above, the maximum statutory period v re to reply within the set or extended period for reply will, by statute reply received by the Office later than three months after the mailing ed patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be tin y within the statutory minimum of thirty (30) day will apply and will expire SIX (6) MONTHS from , cause the application to become ABANDONE	nely filed rs will be considered timely. the mailing date of this com D (35 U.S.C. § 133).	munication.
Status	,			
· · · · · ·	Responsive to communication(s) filed on <u>02 Secondary</u> This action is FINAL . 2b) This Since this application is in condition for allowed closed in accordance with the practice under Expression 1.	action is non-final. nce except for formal matters, pro		nerits is
Dispositi	ion of Claims			
5)□ 6)⊠ 7)□	Claim(s) <u>1-25</u> is/are pending in the application. 4a) Of the above claim(s) <u>16-25</u> is/are withdraw Claim(s) is/are allowed. Claim(s) <u>1-3,7-13 and 15</u> is/are rejected. Claim(s) <u>4-6 and 14</u> is/are objected to. Claim(s) are subject to restriction and/o	vn from consideration.		
Applicati	on Papers			
10)⊠	The specification is objected to by the Examine The drawing(s) filed on <u>09 October 2003</u> is/are: Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the Ex	a) \boxtimes accepted or b) \square objected drawing(s) be held in abeyance. Section is required if the drawing(s) is ob	e 37 CFR 1.85(a). jected to. See 37 CFR	R 1.121(d).
Priority ι	under 35 U.S.C. § 119			
a)l	Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority document: 2. Certified copies of the priority document: 3. Copies of the certified copies of the priority document: application from the International Bureausee the attached detailed Office action for a list	s have been received. s have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this National Si	tage
2) Notic	t(s) e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date 10/09/03.	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	ate	52)

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DETAILED ACTION

Election/Restriction

1. Applicant's election without traverse of Group II, claims 1-15 in the Paper filed

09/02/2004 is acknowledged. The requirement having been made, and applicant having

elected without traverse, the requirement is hereby made final.

Applicant suggests that withdrawn claims 16-25 are obvious over elected claims 1-

15. Applicant is urged not to give up so easily. With regard to claim 16 and claims de-

pendent therefrom, the text of claims 1-15 supplies no suggestion or motivation to grind

the grooves of claims 1-15 when one could just as easily etch them. With regard to

claim 17 and claims dependent therefrom, the text of claims 1-15 supplies no sugges-

tion or motivation to etch the grooves of claims 1-15 when one could just as easily grind

them.

Oath/Declaration

2. The oath/declaration filed on 10/09/2003 is acceptable.

Drawings

3. The formal drawings filed on 10/09/2003 are acceptable.

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Priority

4. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

Information Disclosure Statement

5. The Information Disclosure Statement filed on 10/09/2003 has been considered.

Specification

6. The title of the invention is not descriptive. A new title is required that is clearly indicative of the invention to which the claims are directed.

Claim Rejections - 35 USC § 102

7. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless --

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

A. Claims 1-3 and 7-9 are rejected under 35 U.S.C. 102(b) as being anticipated by KNECHT ET AL. (4,905,575).

With regard to claims 1-3 and 7, Knecht et al. discloses a semiconductor device 70 having an element forming region 71 where a semiconductor element is formed and an

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element non-forming region 76 where no semiconductor element is formed, on a front surface of a silicon substrate 72, comprising a plurality of grooves 75 each having substantially uniform width from a bottom portion to an opening portion of that groove 75, formed parallel to each other in a portion of a rear surface of said substrate 72 corresponding to said element non-forming region 76. Note figure 6 of Knecht et al.

With regard to claims 1-3 and 8, Knecht et al. discloses a semiconductor device 80 having an element forming region 84 where a semiconductor element 81 is formed and an element non-forming region 87 where no semiconductor element is formed, on a front surface of a silicon substrate 82, comprising a plurality of grooves 85 each having a wider width in an opening portion than in a bottom portion of that groove 85, formed parallel to each other in a portion of a rear surface of said substrate 82 corresponding to said element non-forming region 87. Note figure 7 of Knecht et al.

With regard to claims 1-3 and 9, Knecht et al. discloses a semiconductor device 90 having an element forming region 94 where a semiconductor element 91 is formed and an element non-forming region 97 where no semiconductor element formed, on a front surface of a silicon substrate 92, comprising a plurality of grooves 95 having bottom portions with curved surfaces, formed parallel to each other in a portion of a rear surface of said substrate 92 corresponding to said element non-forming region 97. Note figure 8 of Knecht et al.

B. Claims 1, 11-13, and 15 are rejected under 35 U.S.C. 102(b) as being anticipated by WILLIS ET AL. (5,912,427).

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Willis et al. discloses a semiconductor device 500 having silicon substrate 501 coating the rear surface of said silicon substrate 501; a plurality of element forming regions 580 isolated from each other, where semiconductor elements are formed; and an element non-forming region 510, sandwiched between said element forming regions 580, where a semiconductor element is not formed, on a front surface of said silicon substrate 501, said semiconductor device 500 comprising a groove 503 formed in a portion of a rear surface of said substrate 501 corresponding to said element non-forming region 510. With regard to claims 13 and 15 Willis et al. further discloses a semiconductor device module comprising said semiconductor device 500, bonded to a bonding substrate 600 that is capable of being curved. Note figure 12 and column 9 lines 1-15 of Willis et al.

C. Claims 1 and 10 are rejected under 35 U.S.C. 102(b) as being anticipated by SILVERBROOK (2001/0012035).

Silverbrook discloses a semiconductor device having an element forming region 3 where a semiconductor element (drive transistors, note paragraph 73) is formed and an element non-forming region 21 where no semiconductor element is formed, on a front surface of a silicon substrate 2; said semiconductor device comprising a groove 34, filled with a material 53 softer than said silicon substrate 2, formed in a portion of a rear surface of said substrate 2 corresponding to said element non-forming region 21. Note figures 16-19 and paragraphs 55,73,85,86, and 90 of Silverbrook.

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Allowable Subject Matter

8. Claims 4-6 and 14 are objected to as being dependent upon a rejected base claim,

but would be allowable if rewritten in independent form including all of the limitations of

the base claim and any intervening claims.

Conclusion

9. Any inquiry concerning this communication or earlier communications from the ex-

aminer should be directed to Thomas L Dickey whose telephone number is 571-272-

1913. The examiner can normally be reached on Monday-Thursday 8-6.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's su-

pervisor, Nathan J Flynn can be reached on 571-272-1915. The fax phone number for

the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent

Application Information Retrieval (PAIR) system. Status information for published appli-

cations may be obtained from either Private PAIR or Public PAIR. Status information

for unpublished applications is available through Private PAIR only. For more informa-

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on access to the Private PAIR system, contact the Electronic Business Center (EBC) at

866-217-9197 (toll-free).

TLD 09/04

> Minhloan Tran Primary Examiner

Lan Town

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